



# PMEG060V030EPE-Q

60 V, 3 A low  $V_F$  Schottky barrier rectifier

19 July 2022

Product data sheet

## 1. General description

Planar Low  $V_F$  Schottky barrier rectifier encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Very low forward voltage
- High power capability due to clip-bonding technology
- Small and thin SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

## 3. Applications

- High efficiency DC-to-DC conversion
- Low voltage rectification
- Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- OR-ing

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{sp} \leq 174$ °C	-	-	3	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	60	V
$V_F$	forward voltage	$I_F = 3$ A; pulsed; $T_j = 25$ °C	[1]	460	530	mV
$I_R$	reverse current	$V_R = 60$ V; pulsed; $T_j = 25$ °C	[1]	75	200	$\mu$ A

[1] Very short pulse, in order to maintain a stable junction temperature.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	 CFP15B (SOT1289B)	 aaa-009063
2	A	anode		
3	K	cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG060V030EPE-Q	CFP15B	plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	<a href="#">SOT1289B</a>

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG060V030EPE-Q	060V U03E

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	60	V
$I_F$	forward current	$\delta = 1; T_{sp} \leq 173\text{ °C}$		-	4.2	A
$I_{F(AV)}$	average forward current	$\delta = 0.5; f = 20\text{ kHz; square wave; } T_{sp} \leq 174\text{ °C}$		-	3	A
$I_{FSM}$	non-repetitive peak forward current	half sine-wave pulse; $t_p = 8.3\text{ ms; half sine wave; } T_{j(\text{init})} = 25\text{ °C}$		-	120	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	-	1.66	W
			[2]	-	2.15	W
$T_j$	junction temperature			-	175	°C
$T_{amb}$	ambient temperature			-55	175	°C
$T_{stg}$	storage temperature			-65	175	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W
			[1] [3]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	3	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

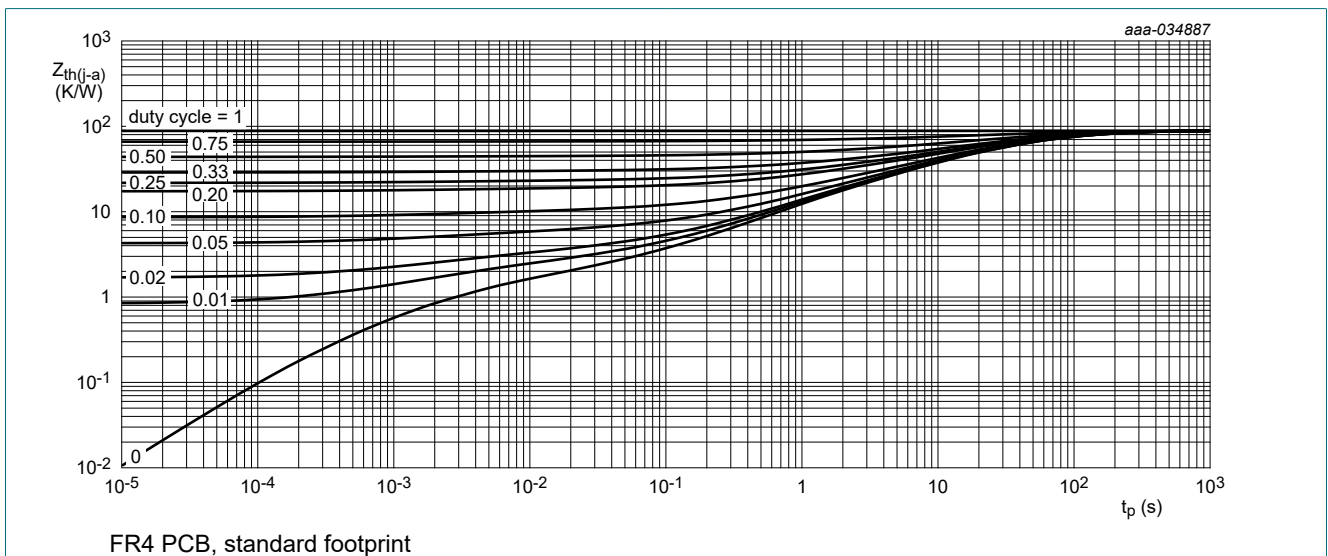


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

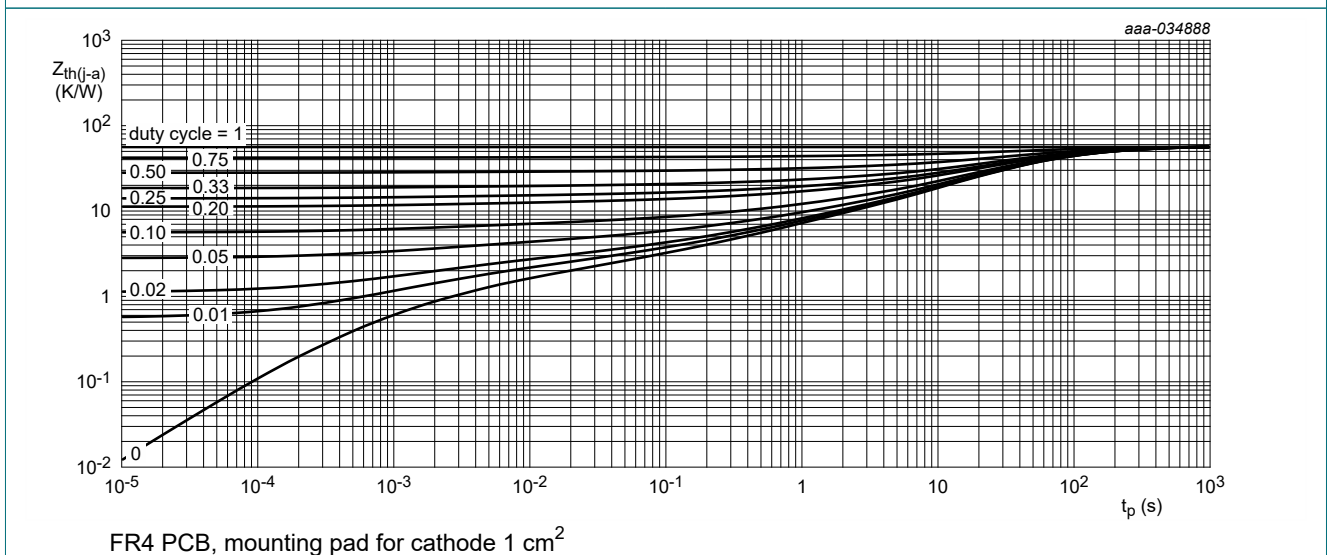


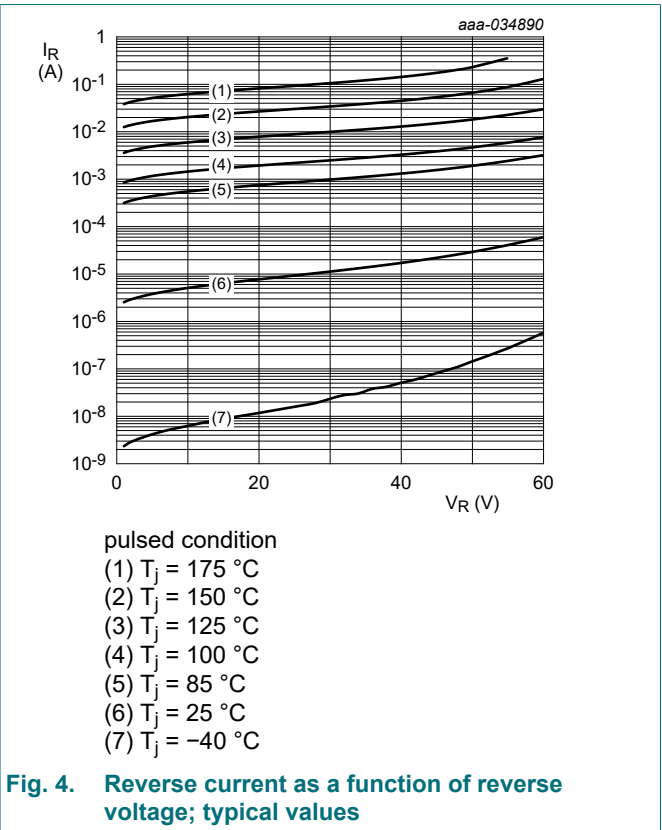
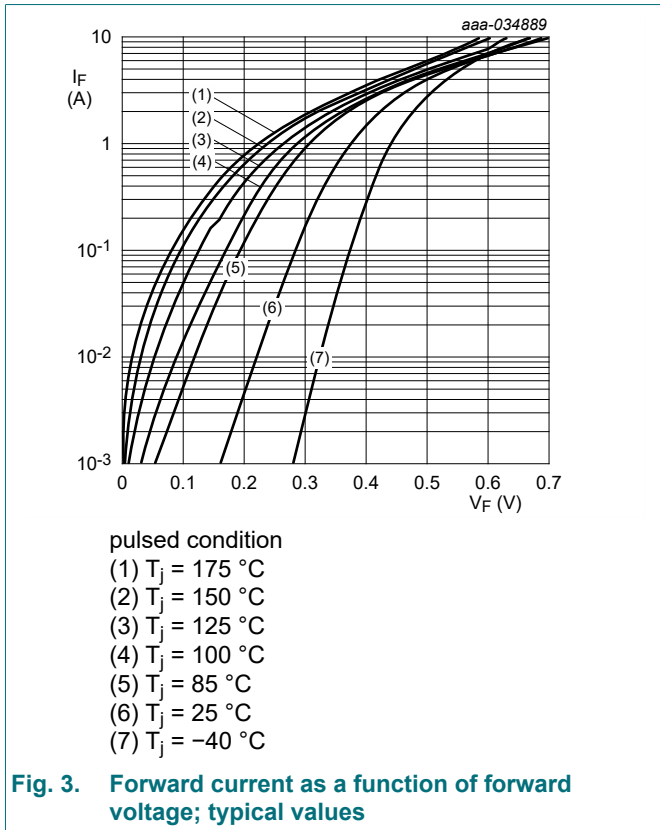
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

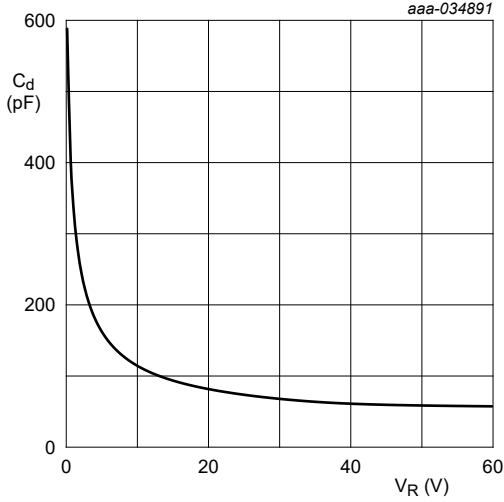
### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 3 \text{ mA}$ ; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	60	-	V	
$V_F$	forward voltage	$I_F = 1 \text{ A}$ ; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	375	440	mV
		$I_F = 2 \text{ A}$ ; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	420	500	mV
		$I_F = 3 \text{ A}$ ; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	460	530	mV
		$I_F = 3 \text{ A}$ ; pulsed; $T_j = -40 \text{ }^\circ\text{C}$	[1]	-	505	600	mV
		$I_F = 3 \text{ A}$ ; pulsed; $T_j = 125 \text{ }^\circ\text{C}$	[1]	-	400	490	mV
$I_R$	reverse current	$V_R = 60 \text{ V}$ ; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	75	200	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_j = 25 \text{ }^\circ\text{C}$		-	323	-	pF
		$V_R = 10 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_j = 25 \text{ }^\circ\text{C}$		-	113	-	pF
$t_{rr}$	reverse recovery time step recovery	$I_F = 0.5 \text{ A}$ ; $I_R = 0.5 \text{ A}$ ; $I_{R(\text{meas})} = 0.1 \text{ A}$ ; $T_j = 25 \text{ }^\circ\text{C}$		-	12	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 100 \text{ A}/\mu\text{s}$ ; $I_F = 3 \text{ A}$ ; $V_R = 30 \text{ V}$		-	10	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}$ ; $dI_F/dt = 20 \text{ A}/\mu\text{s}$ ; $T_j = 25 \text{ }^\circ\text{C}$		-	344	-	mV

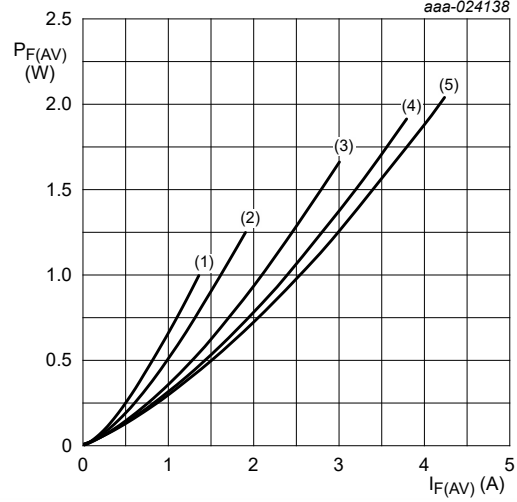
[1] Very short pulse, in order to maintain a stable junction temperature.





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

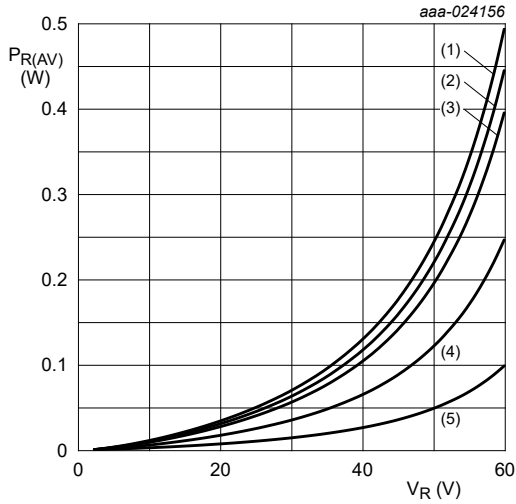
**Fig. 5. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 100 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 0.8$
- (5)  $\delta = 1$

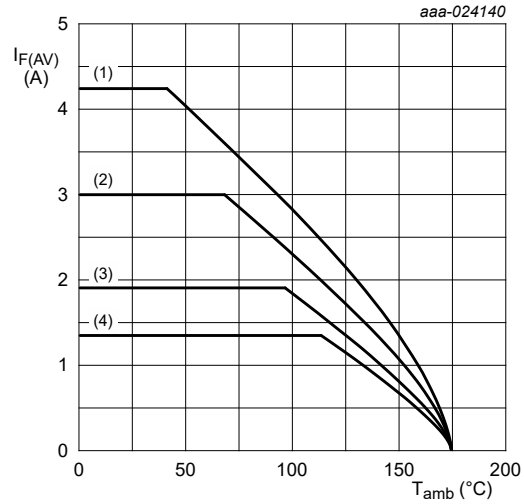
**Fig. 6. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 100 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$
- (5)  $\delta = 0.2$

**Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values**



FR4 PCB, standard footprint

$T_j = 175 \text{ }^\circ\text{C}$

- (1)  $\delta = 1; \text{DC}$
- (2)  $\delta = 0.5; f = 20 \text{ kHz}$
- (3)  $\delta = 0.2; f = 20 \text{ kHz}$
- (4)  $\delta = 0.1; f = 20 \text{ kHz}$

**Fig. 8. Average forward current as a function of ambient temperature; typical values**

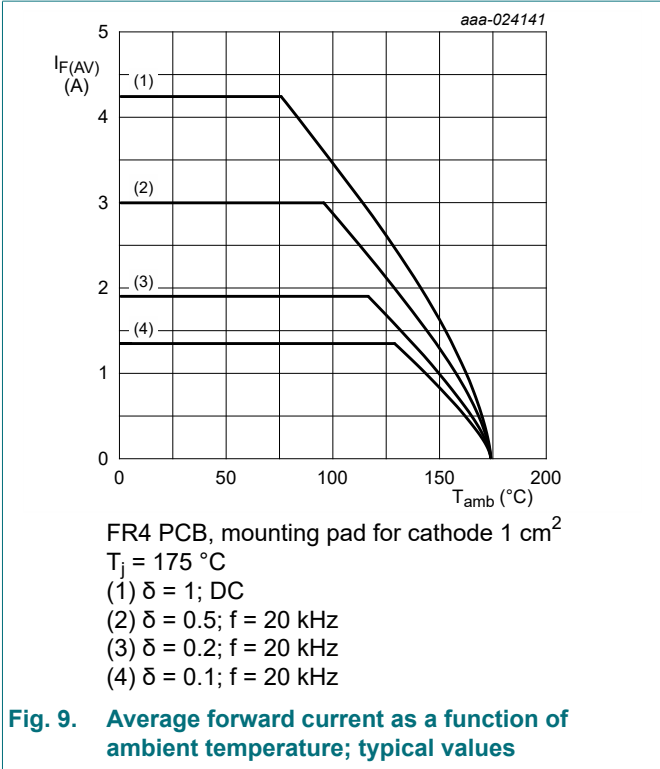


Fig. 9. Average forward current as a function of ambient temperature; typical values

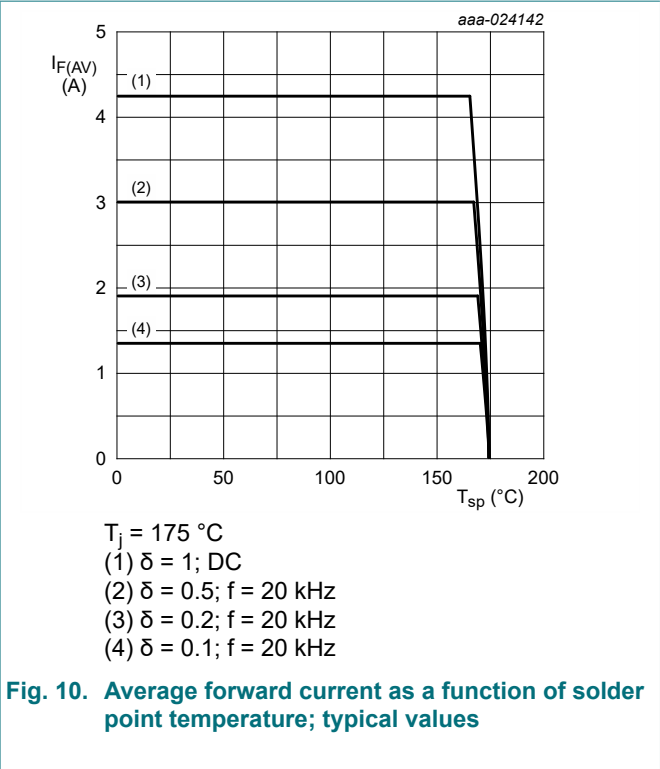


Fig. 10. Average forward current as a function of solder point temperature; typical values

### 11. Test information

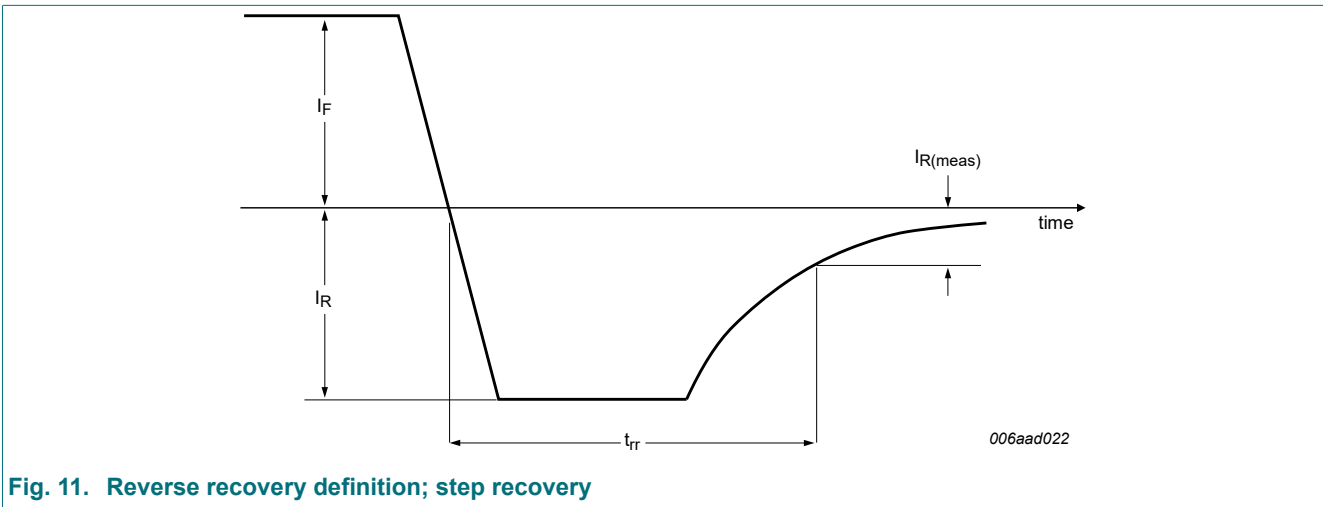


Fig. 11. Reverse recovery definition; step recovery



Fig. 12. Reverse recovery definition; ramp recovery



Fig. 13. Forward recovery definition



Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta}$$

with  $I_{RMS}$  defined as RMS current.

### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline

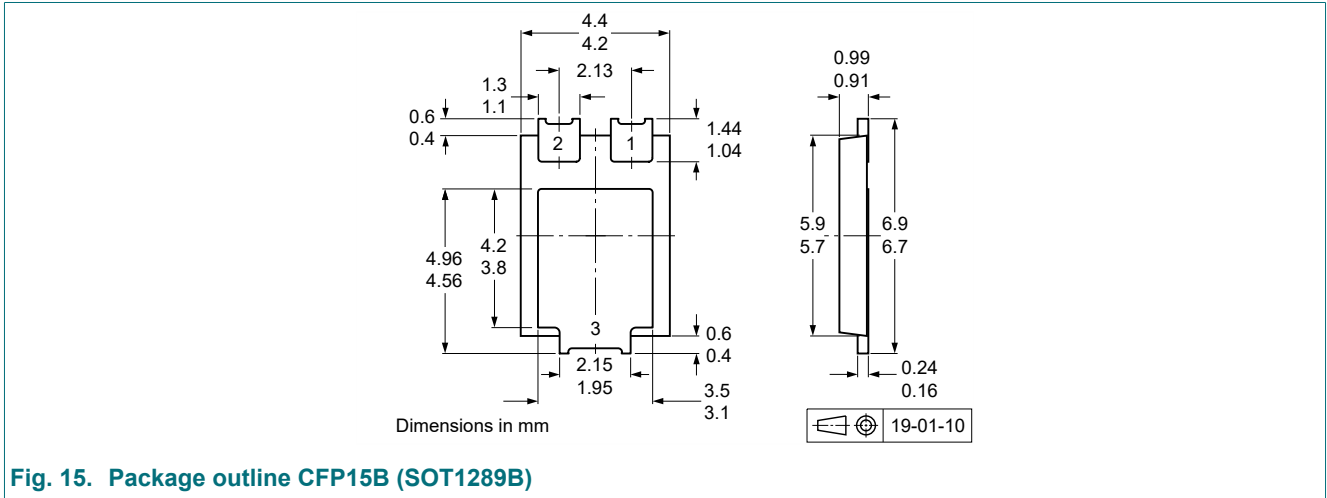


Fig. 15. Package outline CFP15B (SOT1289B)

## 13. Soldering

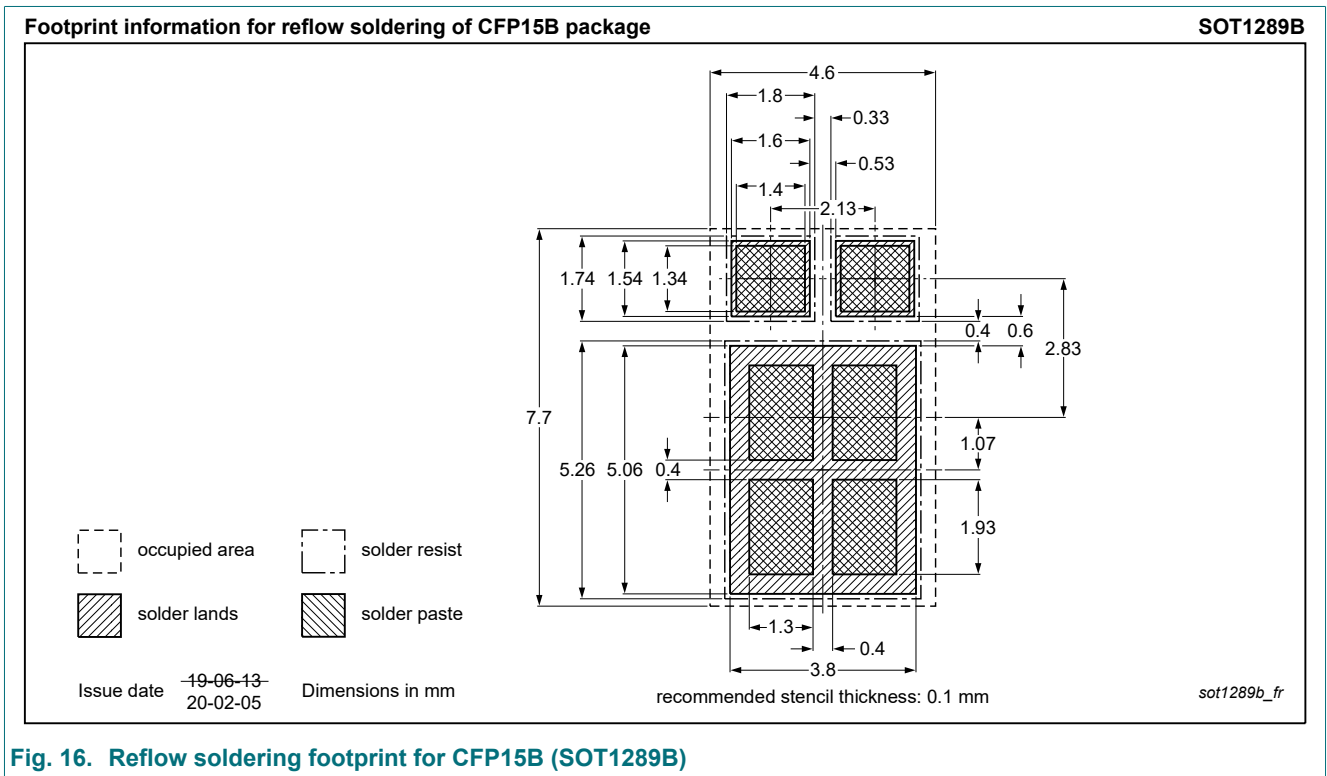


Fig. 16. Reflow soldering footprint for CFP15B (SOT1289B)



## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG060V030EPE-Q v.1	20220719	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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